

### Features

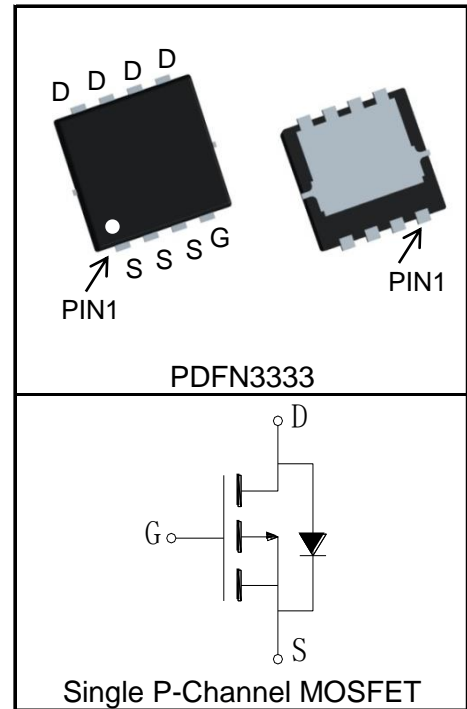
- -30V/-45A,  
 $R_{DS(ON)} = 7m\Omega(Typ.)@V_{GS}=-10V$   
 $R_{DS(ON)} = 10m\Omega(Typ.)@V_{GS}=-4.5V$
- Low  $R_{DS(ON)}$
- Super High Dense Cell Design
- Fast Switching Speed
- 100% avalanche tested

### Applications

- Switching Application Systems



### Pin Description



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit	
<b>Common Ratings</b> ( $T_C=25^\circ C$ Unless Otherwise Noted)				
$V_{DSS}$	Drain-Source Voltage	-30	V	
$V_{GSS}$	Gate-Source Voltage	$\pm 25$		
$T_J$	Maximum Junction Temperature	150	$^\circ C$	
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$	
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ C$	-45	A
<b>Mounted on Large Heat Sink</b>				
$I_{DP}^{①}$	300 $\mu s$ Pulse Drain Current Tested	$T_C=25^\circ C$	-180	A
$I_D^{②}$	Continuous Drain Current@ $T_C(V_{GS}=-10V)$	$T_C=25^\circ C$	-45	A
		$T_C=100^\circ C$	-28	
	Continuous Drain Current@ $T_A(V_{GS}=-10V)^{③}$	$T_A=25^\circ C$	-14	
		$T_A=70^\circ C$	-11	
$P_D$	Maximum Power Dissipation@ $T_C$	$T_C=25^\circ C$	36	W
		$T_C=100^\circ C$	14	
	Maximum Power Dissipation@ $T_A^{③}$	$T_A=25^\circ C$	3.5	
		$T_A=70^\circ C$	2.3	

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.5	°C/W
$R_{\theta JA}$ ③	Thermal Resistance-Junction to Ambient	35	°C/W
<b>Drain-Source Avalanche Ratings</b>			
$E_{AS}$ ④	Avalanche Energy, Single Pulsed	56	mJ

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  Unless Otherwise Noted)

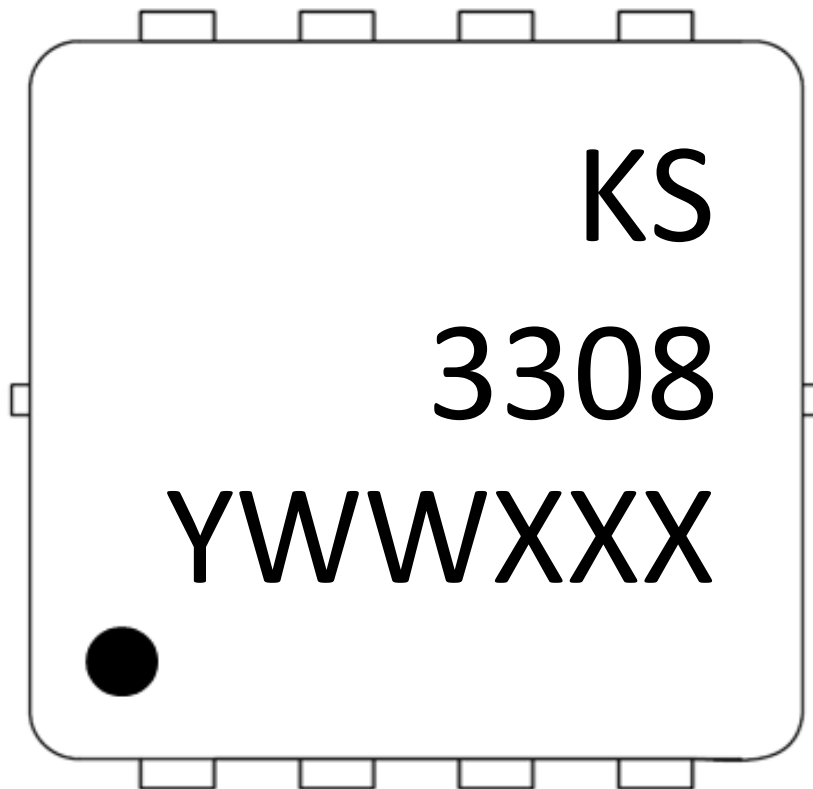
Symbol	Parameter	Test Condition	KS3308MA			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=-250\mu A$	-30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V$			-1	$\mu A$
		$T_J=125^\circ\text{C}$			-30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-1.1	-1.5	-2.3	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$			$\pm 100$	nA
$R_{DS(ON)}$ ⑤	Drain-Source On-state Resistance	$V_{GS}=-10V, I_{DS}=-20A$		7	11	$m\Omega$
		$V_{GS}=-4.5V, I_{DS}=-16A$		10	16	$m\Omega$
<b>Diode Characteristics</b>						
$V_{SD}$ ⑤	Diode Forward Voltage	$I_{SD}=-20A, V_{GS}=0V$		-0.86	-1.2	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=-20A, di_{SD}/dt=100A/\mu s$		27		ns
$Q_{rr}$	Reverse Recovery Charge			58		nC
<b>Dynamic Characteristics</b> ⑥						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$		2.8		$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=-15V,$ Frequency=1.0MHz		3215		$\mu F$
$C_{oss}$	Output Capacitance			380		
$C_{riss}$	Reverse Transfer Capacitance			255		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=-15V, I_{DS}=-20A, V_{GS}=-10V, R_G=3\Omega$		21		ns
$t_r$	Turn-on Rise Time			30		
$t_{d(OFF)}$	Turn-off Delay Time			69		
$t_f$	Turn-off Fall Time			32		
<b>Gate Charge Characteristics</b> ⑥						
$Q_g$	Total Gate Charge	$V_{DS}=-15V, V_{GS}=-10V,$ $I_{DS}=-20A$		51		nC
$Q_{gs}$	Gate-Source Charge			10		
$Q_{gd}$	Gate-Drain Charge			13		

**Notes:**

- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 40A.
- ③When mounted on 1 inch square copper board,  $t \leq 10\text{sec}$ .
- ④Limited by  $T_{J\text{max}}$ ,  $I_{AS} = -15\text{A}$ ,  $L = 0.5\text{mH}$ ,  $V_{DD} = -20\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .
- ⑤Pulse test; Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- ⑥Guaranteed by design, not subject to production testing.

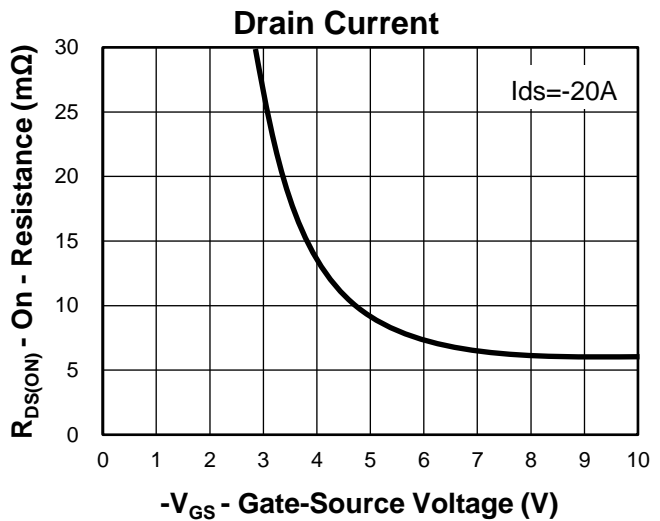
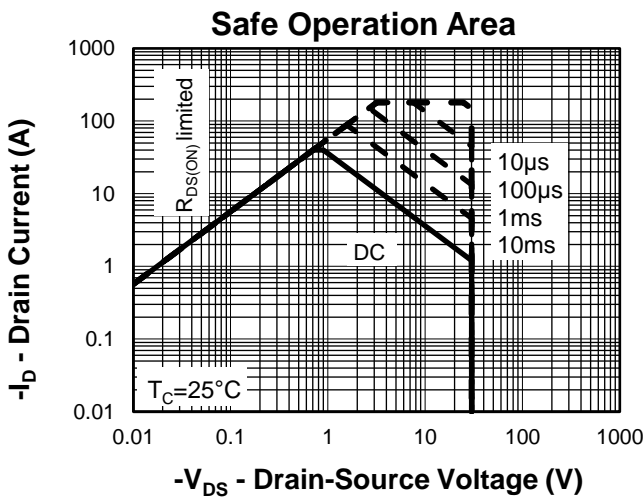
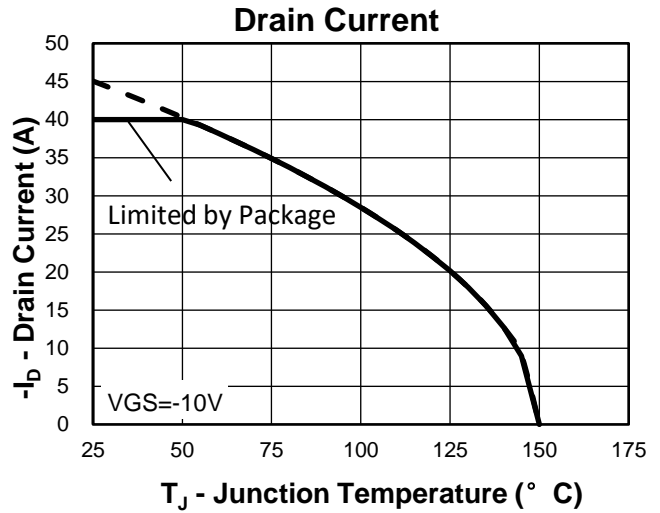
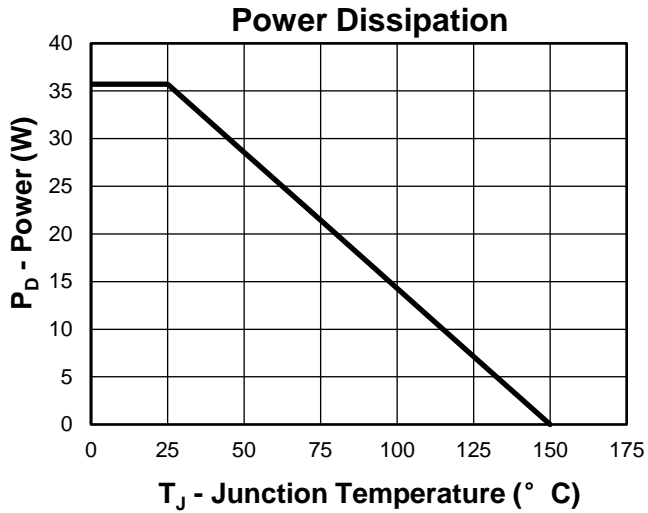
**Ordering and Marking Information**

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS3308MA	PDFN3333	Tape&Reel	5000	13"	12mm

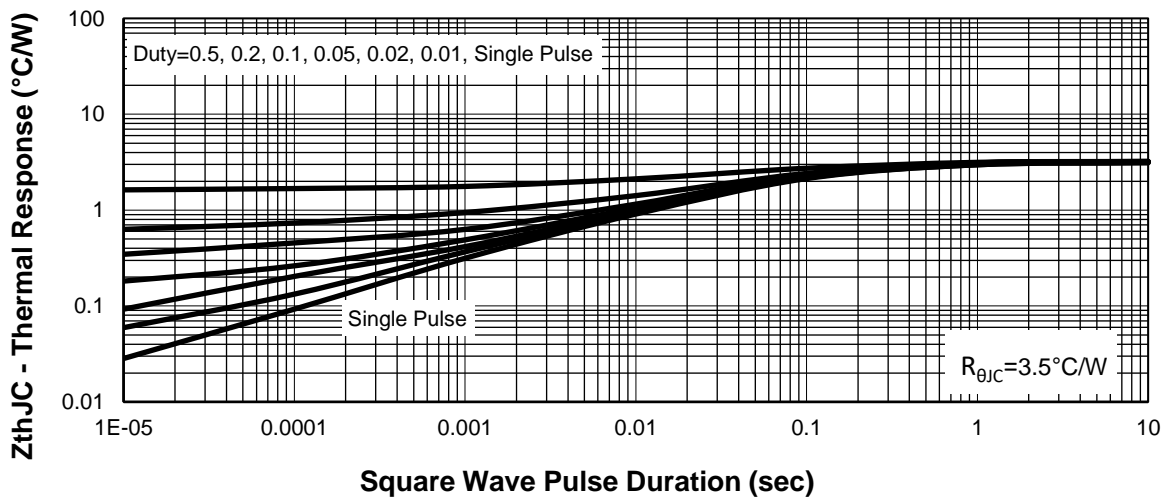


1st Line: Kwansemi Code(KS)  
 2nd Line: Part Number(3308)  
 3rd Line: Lot Number(YWWXXX)

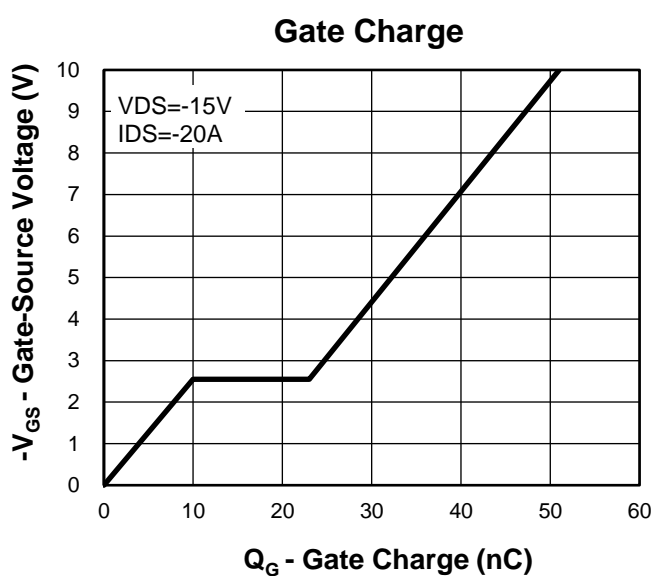
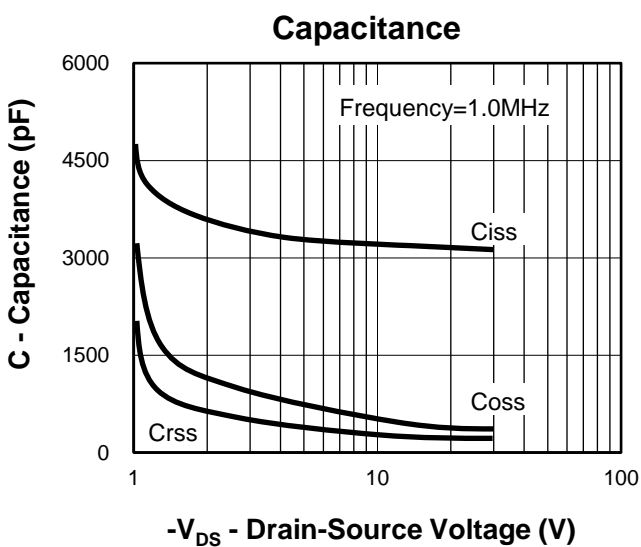
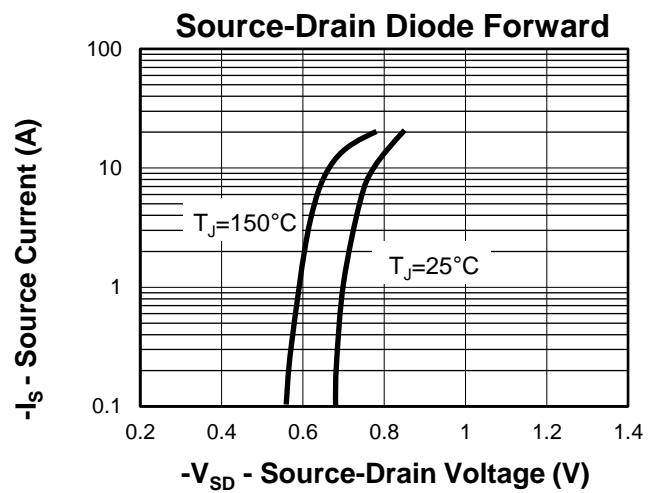
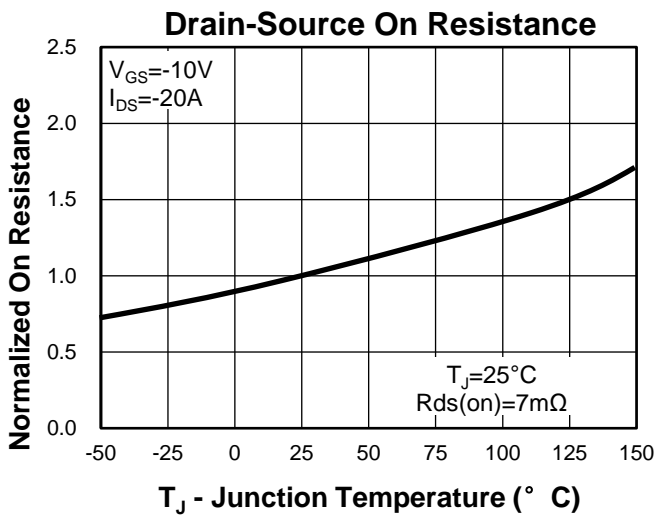
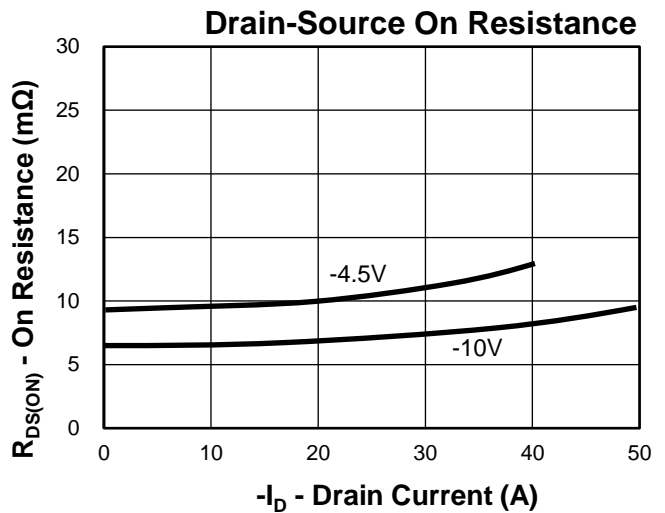
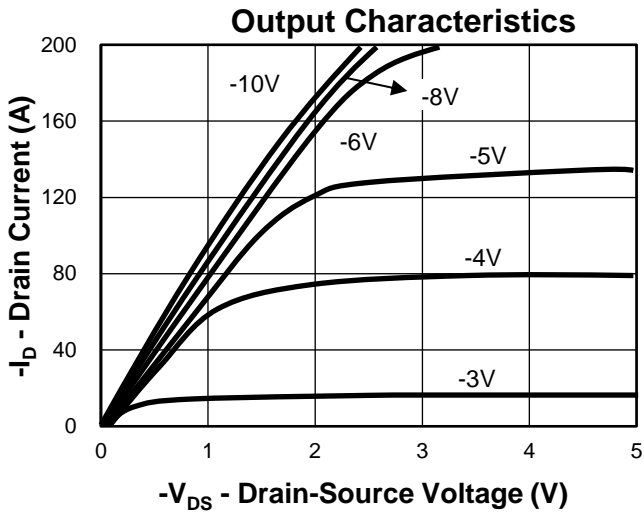
### Typical Characteristics

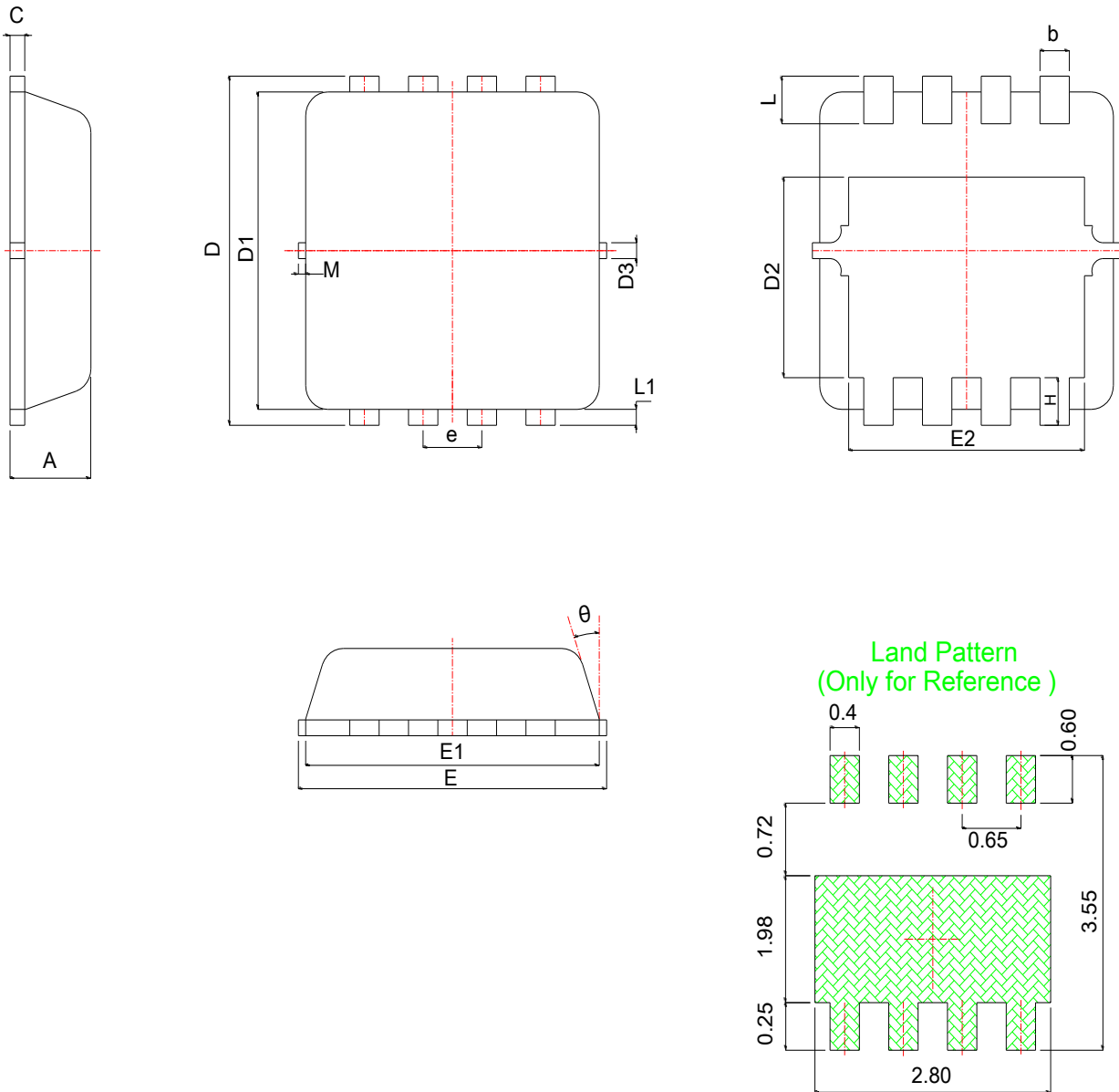


### Thermal Transient Impedance



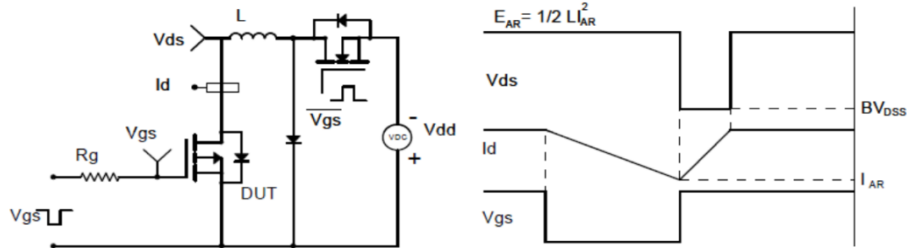
Typical Characteristics



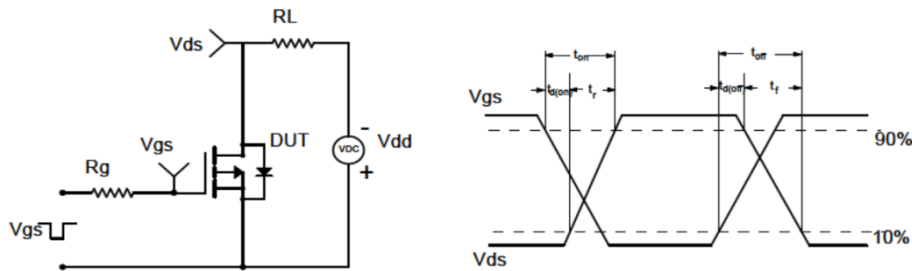
**Package Information**
**PDFN3333**


SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	0.67	0.78	0.88	0.026	0.031	0.035	E1	3.05	3.15	3.25	0.120	0.124	0.128
b	0.25	0.30	0.35	0.010	0.012	0.014	E2	2.25	2.45	2.65	0.089	0.096	0.104
c	0.10	0.15	0.25	0.004	0.006	0.010	e	0.65BSC			0.026BSC		
D	3.15	3.35	3.55	0.124	0.132	0.140	H	0.30	0.40	0.50	0.012	0.016	0.020
D1	3.00	3.10	3.20	0.118	0.122	0.126	L	0.30	0.40	0.50	0.012	0.016	0.020
D2	1.53	1.73	1.93	0.060	0.068	0.076	L1	*	0.13	*	*	0.005	*
D3	*	0.13	*	*	0.005	*	theta	*	10°	12°	*	10°	12°
E	3.10	3.30	3.50	0.122	0.130	0.138	M	*	*	0.15	*	*	0.006

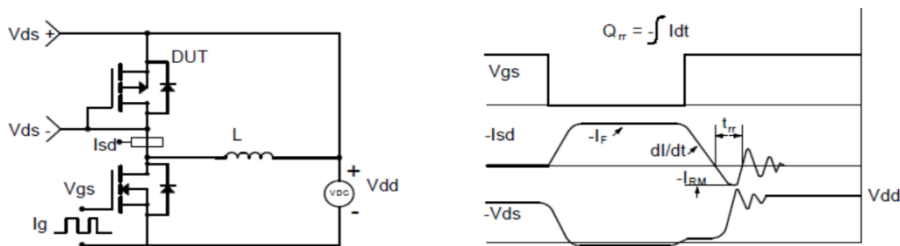
### Avalanche Test Circuit and Waveforms



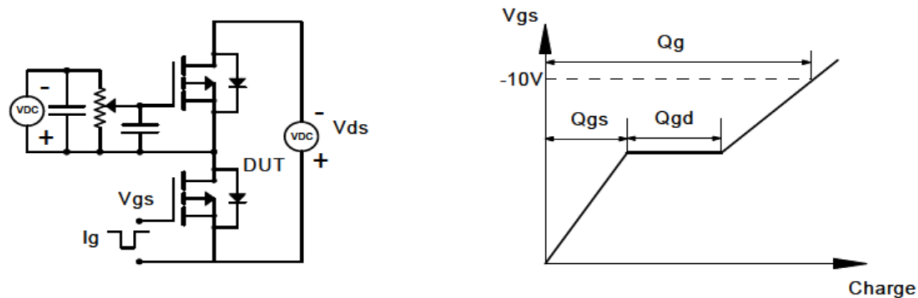
### Switching Time Test Circuit and Waveforms



### Diode Recovery Test Circuit and Waveforms



### Gate Charge Test Circuit and Waveform



### Customer Service

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